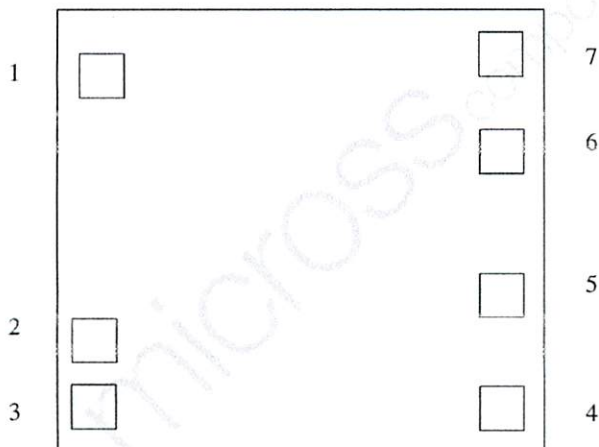


**PAD FUNCTIONS**

1. Inverting Input
2. Non-inverting Input
3. -Vs
4. V<sub>L</sub>
5. Output
6. +Vs
7. V<sub>H</sub>



The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Back potential is the electrical potential of the substrate (bulk silicon), which may not require an electrical connection unless stated in this drawing.

**Note: 1 mil = 0.001inch**

<u>APPROVED</u>  GB ..... DATE: 13/12/12	<h1>OPA699</h1>  <h2>Texas Instruments</h2>	<u>DIE INFORMATION</u> DIMENSIONS (Mils): 38 x 37 BOND PADS (Mils): MASK REF: GEOMETRY: CIC60152 BACK POTENTIAL: -Vs (or leave Floating)
<u>SERIAL NUMBER</u> M000948		<u>METALLISATION</u> TOP: Al BACK: Silicon Nitride (or bare Si if backlapped)